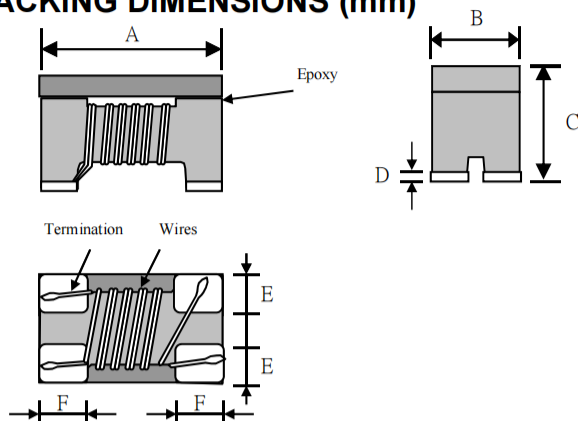


PACKING DIMENSIONS (mm)



3225	Dimensions
A	3.2 ± 0.2
B	2.5 ± 0.2
C	2.2 ± 0.2
D	0.2 ± 0.1
E	0.80 Typ
F	0.65 Typ

EXPLANATION OF PART NUMBERS

1	2	3	4	5	6	7	8	9	10	11	12
S	W	M	3	2	2	5	S	1	0	2	H
(1)			(2)						(3)		

(1) Product name

(2) Shapes and dimensions

(3) Impedance 【 at 100MHz 】

102:1000 Ω

ELECTRICAL CHARACTERISTICS

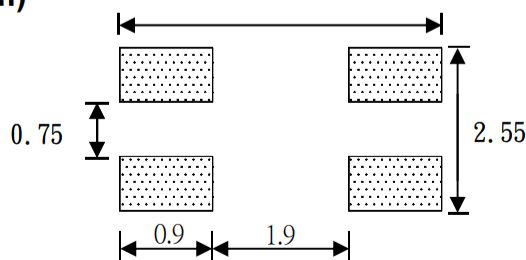
P/N	Z(Ω)	DCR (Ω)	Rated current	Rated Voltage	Insulation Resistance
	Common Mode				
	Impedance				
	at 100MHz				
SMW3225S161HTE	160	[Max]	Idc(A)	Vdc	IR
SMW3225S601HTE	600		[Max]	(V)Typical	(MΩ)Min.
SMW3225S102HTE	1000				

Operating temperature : -25 to +85°C

Storage temp. and humidity : -40 to +85°C ,70%RH max

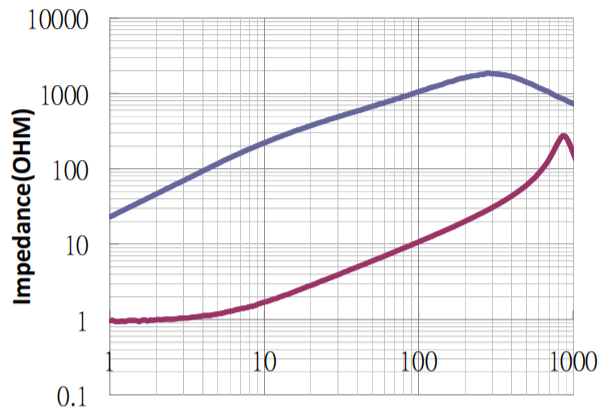
Typical Heat Rating DC Current would cause an approximately ΔT of 40°C

Recommended Footprint(mm)

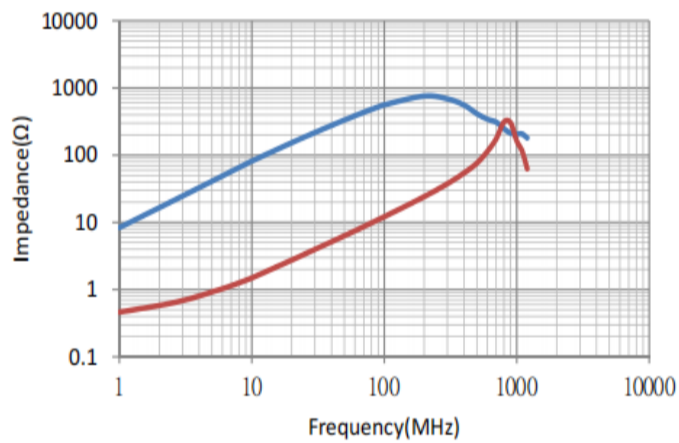


PERFORMANCE CURVES

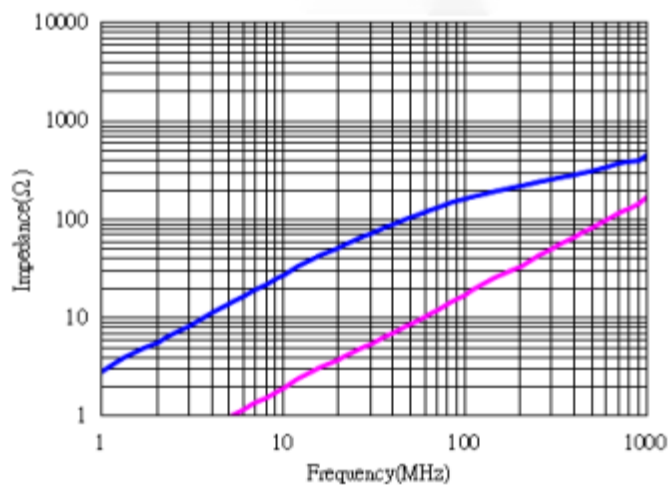
SMW3225S102HTE



SWM3225S601HTE



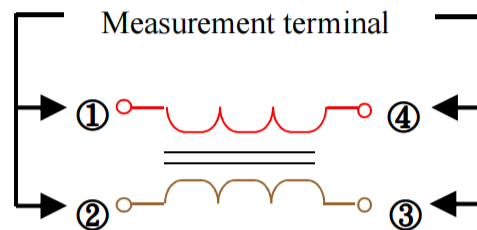
SMW3225S161HTE



Test Equipment

Impedance

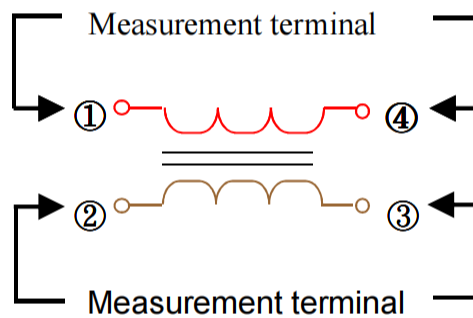
Measured by using Agilent 4291A RF Impedance Analyzer.



DC Resistance

Measurement terminal

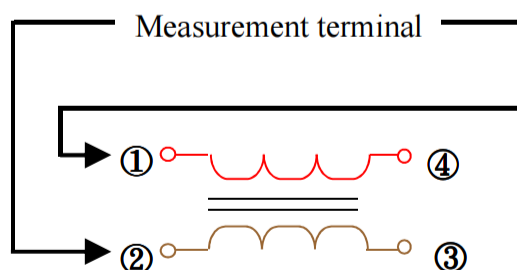
Measured by using Chroma 16502 mill ohm meter.



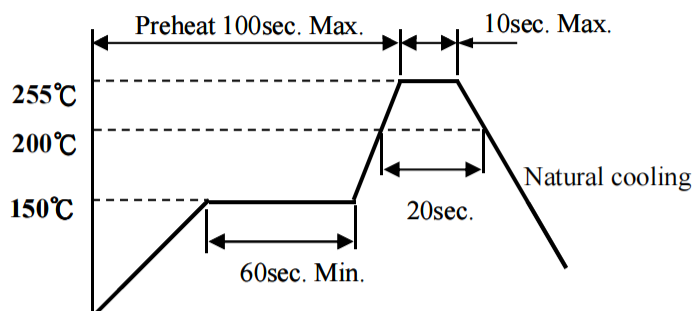
Insulation Resistance

Measured by using Chroma 19073

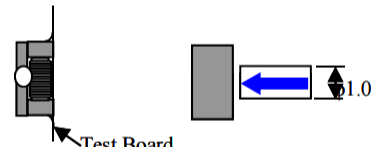
Measurement voltage : 50v ,Measurement time : 60 sec.



RECOMMENDED SOLDERING TEMP. GRAPH



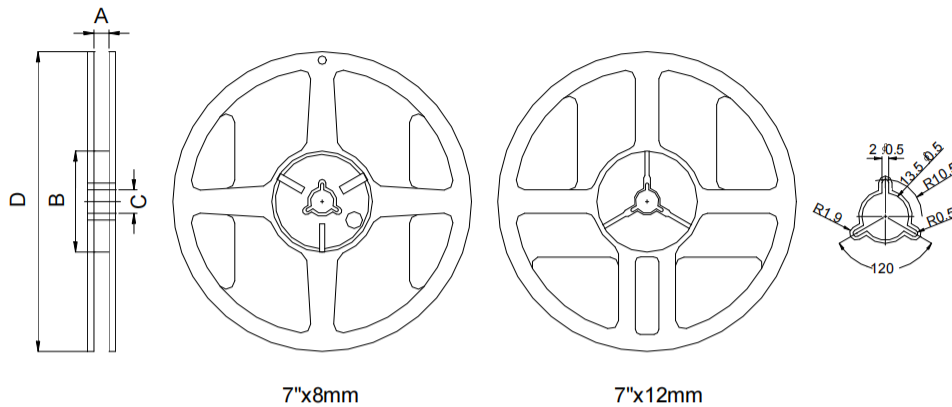
MECHANICAL RELIABILITY

TEST	Specification & Requirement		Method Used
Solderability	The surface of terminal/pin tested shall be covered with new solder by 90%		Solder heat proof: Preheating: 150 ±10°C 60 seconds Soldering: 245 ±5°C for 4 ±1 sec
Solder Heat Resistance	Components should have not evidence of electrical and mechanical damage Impedance: within ±15% of initial value		Preheating: 150°C 60secs Solder temperature: 260±5°C Flux: rosin Dip time: 10±0.5 secs
Terminal strength	Series No.	F (Kg)	Solder a chip to test substrate and then laterally apply a force in the arrow direction 
	1608	0.5	
	2012	0.5	
	3216	1.0	
	3225	1.0	

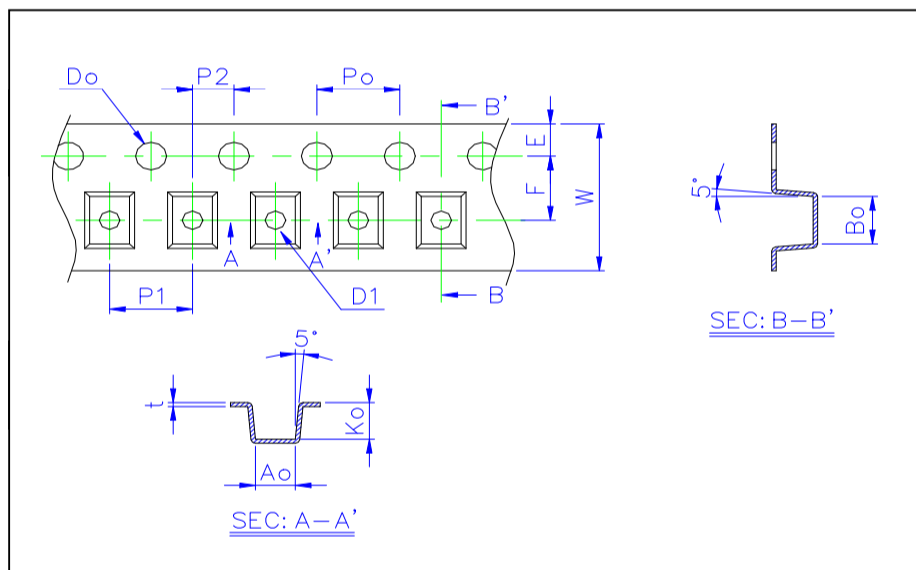
ENDURANCE RELIABILITY

TEST	Specification & Requirement	Method Used
Thermal Shock	Impedance change within ± 15% Without mechanical damage	-65°C, (30 mins) -> room temp. (2 mins) -> 125°C, (30 mins) -> room temp. (2 mins) 50 cycles
Humidity Resistance	Impedance change within ± 15% Without mechanical damage	Apply IDC current @ 60°C ambient Humidity: 90% Duration: 168 hrs
Low Temp. Storing	Impedance change within ± 15% Without mechanical damage	Storing Temp. -40 ±2 °C for total 168 +5/-0 hours
High Temp. Storing	Impedance change within ± 15% Without mechanical damage	Storing Temp. 125 ±2 °C for total 168 +5/-0 hours

Reel Dimension & Tape Dimension



Type	A(mm)	B(mm)	C(mm)	D(mm)
7"x8mm	9.0±0.5	60±2	13.5±0.5	178±2
7"x12mm	13.5±0.5	60±2	13.5±0.5	178±2



Size	Ao(mm)	Bo(mm)	Ko(mm)	W(mm)	E(mm)	F(mm)	Po(mm)	P1(mm)	Do(mm)
1608	1.65±0.10	1.00±0.10	1.18±0.10	8.00±0.20	1.75±0.10	3.50±0.05	4.0±0.05	4.0±0.10	none
2012	2.35±0.10	1.50±0.10	1.45±0.10	8.00±0.20	1.75±0.10	3.50±0.05	4.0±0.05	4.0±0.10	1.0±0.1
3216	3.50±0.10	1.88±0.10	2.10±0.10	8.00±0.20	1.75±0.10	3.50±0.05	4.0±0.05	4.0±0.10	1.0±0.1
3225	3.60±0.10	2.80±0.10	2.20±0.10	8.00±0.20	1.75±0.10	3.50±0.05	4.0±0.05	4.0±0.10	1.0±0.1

Packaging Quantity

Chip Size	3225
8mm/ Reel	2000